

ABSTRACT

A semiconductor apparatus is disclosed.

The semiconductor apparatus comprises a substrate
5 with a pad, an internal circuitry region, and a protection resistance formed on the substrate. The pad is connected to a first electrode of the protection resistance by wiring, the internal circuitry region is connected to a second electrode
10 of the protection resistance by wiring, and the protection resistance protects the internal circuitry region from electrostatic discharging.
The semiconductor apparatus is characterized in
that the pad is placed between the protection
15 resistance and the internal circuitry region.